INTERFERENCE

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L18	0	((test same pattern same wafer) and configur$4 and adjust$4 and (layout or laid adj out) and (region or area) and sensitive and fabricat$4).CLM.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:23

Results for "((test <and> pattern <and> wafer <and> fabrication <and> configuration)<i..."
Your search matched **2** of **1243738** documents.
A maximum of **100** results are displayed, **25** to a page, sorted by **Relevance** in **Descending** order.

» Search Options

View Session History

New Search

Modify Search

((test <and> pattern <and> wafer <and> fabrication <and> configuration)<in>metadat

Check to search only within this results set

Display Format: Citation Citation & Abstract

» Key

IEEE JNL	IEEE Journal or Magazine
IEE JNL	IEE Journal or Magazine
IEEE CNF	IEEE Conference Proceeding
IEE CNF	IEE Conference Proceeding
IEEE STD	IEEE Standard

Select Article Information

1. **Sensor for monitoring the rinsing of patterned wafers**
Jun Yan; Seif, D.; Raghavan, S.; Vermeire, B.; Barnaby, H.J.; Peterson, T.; Sh
Semiconductor Manufacturing, IEEE Transactions on
Volume 17, Issue 4, Nov. 2004 Page(s):531 - 537
Digital Object Identifier 10.1109/TSM.2004.837001
AbstractPlus | References | Full Text: PDF(1144 KB) IEEE JNL

2. **Large deflection micromechanical scanning mirrors for linear scans and generation**
Schenk, H.; Durr, P.; Haase, T.; Kunze, D.; Sobe, U.; Lakner, H.; Kuck, H.;
Selected Topics in Quantum Electronics, IEEE Journal of
Volume 6, Issue 5, Sept.-Oct. 2000 Page(s):715 - 722
Digital Object Identifier 10.1109/2944.892609
AbstractPlus | References | Full Text: PDF(432 KB) IEEE JNL

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	322	(test same pattern same fabricat$4 same wafer) and configur$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L2	88	(test same pattern same fabricat$4 same wafer) and configur$4 and layout and device	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L3	5	(test same pattern same fabricat$4 same wafer same configur$4) and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L4	58	(pattern same fabricat$4 same wafer same configur$4) and correla$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L5	3	((test near4 pattern) same fabricat$4 same configur$4) and correla$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L6	27	((test near4 pattern) same configur$4) and correla$4 and fabricat$4 and layout	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:45
L7	249	((test near4 pattern) same configur$4) and correla$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 11:42
L8	118	((test near4 pattern) same configur$4) and adjust$4 and (layout or laid adj out)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 11:43

L9	97	((test near4 pattern) same configur$4) and adjust$4 and (layout or laid adj out) and (region or area)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 11:44
L10	8	((test near4 pattern) same configur$4) and adjust$4 and (layout or laid adj out) and (region or area) and "716"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 11:44
L11	5	((test near4 pattern) same configur$4) and adjust$4 and (layout or laid adj out) and (region or area) and fabricat$4 and "716"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:05
L12	16	(test same pattern same wafer) and configur$4 and adjust$4 and (layout or laid adj out) and (region or area) and fabricat$4 and "716"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:06
L13	222	(test same pattern same wafer) and configur$4 and adjust$4 and (layout or laid adj out) and (region or area) and fabricat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:20
L14	28	(test same pattern same wafer) and configur$4 and (adjust$4 same (layout or laid adj out)) and (region or area) and fabricat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:08
L16	7	((test same pattern same wafer) and configur$4 and adjust$4 and (layout or laid adj out) and (region or area) and fabricat$4).CLM.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:22
L19	149	(test same pattern same wafer) and configur$4 and adjust$4 and (layout or laid adj out) and (region or area) and sensitive and fabricat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:24

L20	7	(test same pattern same wafer) and configur$4 and adjust$4 and (layout or laid adj out) and (region or area) and sensitive and fabricat$4 and "716"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 12:25